## Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

### Marketing Name / Model
[List multiple models if applicable.]

HP P24mh 23.8-inch Display

### Purpose
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP's Sustainability Contact.

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Display Board<em>1, Power Board</em>1, Main Board*1</td>
<td>3</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>C605 in SPS board</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>HDMI cable<em>1, DP cable</em>1, VGA cable<em>1, Power cord</em>1, Audio cable*1</td>
<td>5</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

**NOTE:** Add detailed removal procedures including required tools in the sections 3.1 and 3.2.

EL-MF877-00
Template Revision C

Last revalidation date 09-September-2019

HPI instructions for this template are available at EL-MF877-01
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
Weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) |  |  
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0  
Components and waste containing asbestos |  | 0  
Components, parts and materials containing refractory ceramic fibers |  | 0  
Components, parts and materials containing radioactive substances |  | 0

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>Slothead screwdriver</td>
<td>1</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Lay the display on soft desk and push the button of stand to unlock the stand, then pull out the stand form the monitor head.
2. Twist out the screw and separate base and stand.
3. Move rear cover follow the below way.
4. Strip eleven screws from the rear cover, shielding and speaker.
5. Remove speaker, the acetate tapes and aluminum tape from the LVDS/ LED/KP cable.
6. Pull out the LVDS/ LED/KP cables to panel.
7. Take down the shielding from big rear cover.
8. Remove deco from the monitor.
9. Remove the acetate tape and mylar from MB.
10. Pull out the LVDS/ LED/KP/Speaker cables to MB; pull out the MB to PB cable to MB and power board.
11. Strip ten screws from the shielding.
12. Take out MB and power board from the shielding.
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Lay the display on soft desk and push the button of stand to unlock the stand, then pull out the stand from the monitor head.

2. Twist out the screw and separate base and stand.

HPI instructions for this template are available at EL-MF877-01
3. Move rear cover follow the below way.

Dismantle the rear cover first from the marked position.
4. Strip eleven screws from the rear cover, shielding and speaker.

5. Remove speaker, the acetate tapes and aluminum tape from the LVDS/LED/KP cable.

6. Pull out the LVDS/LED/KP cable to panel.
7. Take down the shielding from big rear cover.

8. Remove deco from the monitor.
9. Remove the acetate tape and mylar from MB.

10. Pull out the LVDS/ LED/KP/Speaker cables to MB; pull out the MB to PB cable to MB and power board.
11. Strip ten screws from the shielding.

12. Take out MB and power board from the shielding.